

20-BIT BUS SWITCH

FEATURES:

- Bus switches provide zero delay paths
- Extended commercial range of –40°C to +85°C
- Low switch on-resistance: FST32XL2384 28Ω
- TTL-compatible input and output levels
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- Available in SSOP, TSSOP, and TVSOP Packages

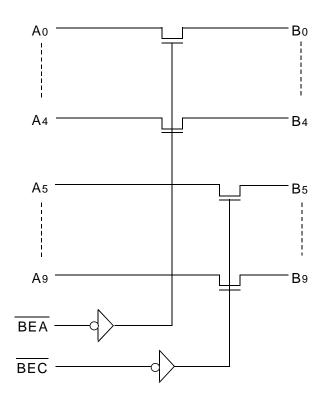
DESCRIPTION:

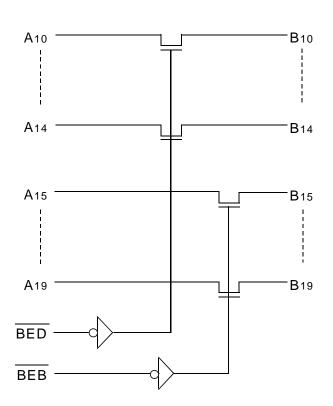
The FST32XL2384 belongs to IDT's family of Bus switches. Bus switch devices perform the function of connecting or isolating two ports without providing any inherent current sink or source capability. Thus they generate little or no noise of their own while providing a low resistance path for an external driver. These devices connect input and output ports through an n-channel FET. When the gate-to-source junction of this FET is adequately forward-biased the device conducts and the resistance between input and output ports is small. Without adequate bias on the gate-to-source junction of the FET, the FET is turned off, therefore with no Vcc applied, the device has hot insertion capability.

The low on-resistance and simplicity of the connection between input and output ports reduces the delay in this path to close to zero.

The FST32XL2384 is a 20-bit TTL-compatible bus switch. The BEx pins provide enable control.

FUNCTIONAL BLOCK DIAGRAM

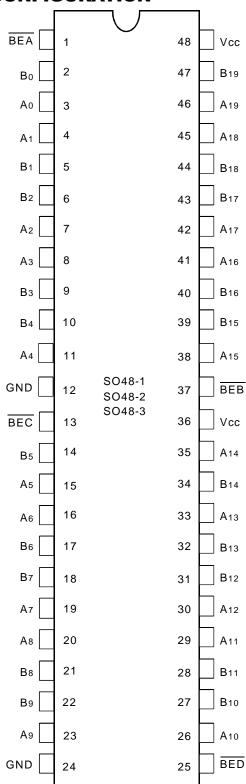




EXTENDED COMMERCIAL TEMPERATURE RANGE

SEPTEMBER 1999

PIN CONFIGURATION



SSOP/ TSSOP/ TVSOP TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Max.	Unit
VTERM(2)	Terminal Voltage with Respect to GND	-0.5 to +7	٧
Tstg	Storage Temperature	-65 to +150	°C
Іоит	Maximum Continuous Channel Current	128	mA
			FST LINK

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. Vcc, Control, and Switch terminals.

CAPACITANCE (1)

Symbol	Parameter	Conditions ⁽²⁾	Тур.	Unit
CIN	Control Input Capacitance		4	pF
CI/O	Switch Input/Output	Switch Off	8	pF
	Capacitance			

NOTES:

- 1. Capacitance is characterized but not tested.
- 2. TA = 25°C, f = 1MHz, VIN = 0V, VOUT = 0V

PIN DESCRIPTION

Pin Names	I/O	Description
A19-A0	I/O	Bus A
B19-B0	I/O	Bus B
BEA	I	Enable, 0-4
BEB	I	Enable, 15-19
BEC	I	Enable, 5-9
BED	I	Enable, 10-14

FUNCTION TABLE(1)

BEA	BEB	B ₀ -B ₄	B15-B19	Description
Н	Н	Hi-Z	Hi-Z	Disconnect
L	Н	A0-A4	Hi-Z	Connect
Н	L	Hi-Z	A15-A19	Connect
L	L	A ₀ -A ₄	A15-A19	Connect
BEC	BED	B5-B9	B10-B14	Description
BEC H	BED H	B 5- B 9 Hi-Z	B10-B14 Hi-Z	Description Disconnect
	Н	Hi-Z	Hi-Z	Disconnect

NOTE:

- 1. H = HIGH
 - L = LOW
 - Z = High-Impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified: Operating Conditions: TA = -40°C to +85°C, Vcc = 5.0V ±10%

Symbol	Parameter	Test Conditions ⁽¹⁾	Test Conditions ⁽¹⁾		Typ. ⁽²⁾	Max.	Unit
VIH	Input HIGH Voltage	Guaranteed Logic HIGH for Control	Guaranteed Logic HIGH for Control Inputs		_	_	V
VIL	Input LOW Voltage	Guaranteed Logic LOW for Control	Guaranteed Logic LOW for Control Inputs		_	0.8	V
Іін	Input HIGH Current	Vcc = Max.	VI = VCC	_	_	±1	μΑ
Iμ	Input LOW Voltage		Vı = GND	_	_	±1	
Гоzн	High Impedance Output Current	Vcc = Max.	Vo = Vcc	_	_	±1	μA
lozL	(3-State Output pins)		Vo = GND	_	_	±1	
los	Short Circuit Current	Vcc = Max., Vo = GND ⁽³⁾	Vcc = Max., Vo = GND ⁽³⁾		300	_	mA
Vik	Clamp Diode Voltage	Vcc = Min., IIN = -18mA	Vcc = Min., IIN = -18mA		-0.7	-1.2	V
Ron	Switch On Resistance ⁽⁴⁾	VCC = Min. VIN = 0.0V	Vcc = Min. VIN = 0.0V		28	40	Ω
		Ion = 30mA					
		VCC = Min. VIN = 2.4V		20	35	48	Ω
	Ion = 15mA						
loff	Input/Output Power Off Leakage	$V_{CC} = 0V$, V_{IN} or $V_O \le 4.5V$	$V_{CC} = 0V$, V_{IN} or $V_O \le 4.5V$		_	1	μA
Icc	Quiescent Power Supply Current	Vcc = Max., Vin = GND or Vcc		_	0.1	3	μΑ

NOTES:

- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Not more than one output should be tested at one time. Duration of the test should not exceed one second.
- 4. Measured by voltage drop between ports at indicated current through the switch.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾			Тур. ⁽²⁾	Max.	Unit
Δlcc	Quiescent Power Supply Current TTL Inputs HIGH	$V_{CC} = Max.$ $V_{IN} = 3.4V^{(3)}$		1	0.5	1.5	mA
ICCD	Dynamic Power Supply Current ⁽⁴⁾	Vcc = Max. Outputs Open Enable Pin Toggling 50% Duty Cycle	VIN = VCC VIN = GND	_	30	40	μΑ/ MHz/ Switch
Ic	Total Power Supply Current ⁽⁶⁾	Vcc = Max. Outputs Open Enable Pins Toggling	VIN = VCC VIN = GND	_	6	8	mA
		(20 Switches Toggling) fi = 10MHz 50% Duty Cycle	VIN = 3.4 VIN = GND	_	7	11	

NOTES:

- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V). All other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- 5. Values for these conditions are examples of the Icc formula. These limits are guaranteed but not tested.
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC

 $IC = ICC + \Delta ICC DHNT + ICCD (fiN)$

Icc = Quiescent Current

 Δ Icc = Power Supply Current for a TTL High Input (VIN = 3.4V)

DH = Duty Cycle for TTL Inputs High

NT = Number of TTL Inputs at DH

ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

fi = Input Frequency

N = Number of Switches Toggling at fi

All currents are in milliamps and all frequencies are in megahertz.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Conditions: TA = -40°C to +85°C, Vcc = $5.0V \pm 10\%$

Symbol	Description	Condition ⁽¹⁾	Min. ⁽²⁾	Тур.	Max.	Unit
tplh	Data Propagation Delay	CL = 50pF	_	_	1.25	ns
tphl	Ai to Bi, Bi to Ai ^(3,4)	$RL = 500\Omega$				
tpzh	Switch Turn on Delay		1.5	_	7.5	ns
tPZL	BEx to Ai, Bi					
tphz	Switch Turn off Delay		1.5	_	5.5	ns
tplz	BEx to Ai, Bi ⁽³⁾					
Qci	Charge Injection ^(5,6)		_	1.5	_	pC

NOTES:

- 1. See test circuit and waveforms.
- 2. Minimum limits guaranteed but not tested.
- 3. This parameter is guaranteed by design but not tested.
- 4. The bus switch contributes no propagation delay other than the RC delay of the on resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 2.5ns for 50pF load. Since this time is constant and much smaller than the rise/fall times of typical driving signals, it adds very little propagation delay to the system. Propagation delay on the bus switch when used in a system is determined by the driving circuit on the driving side of the switch and its interaction with the load on the driven side.
- 5. Measured at switch turn off, load = 50pF in parallel with $10M\Omega$ scope probe, VIN = 0.0 volts.
- 6. Characterized parameter. Not 100% tested.

Switch

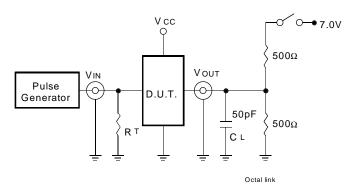
Closed

Open

FCT LINK

TEST CIRCUITS AND WAVEFORMS

TEST CIRCUITS FOR ALL OUTPUTS



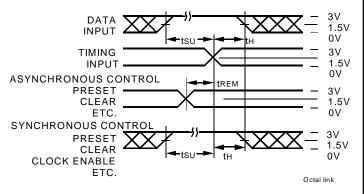
Enable Low

DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to ZouT of the Pulse Generator.

SET-UP, HOLD, AND RELEASE TIMES



PULSE WIDTH

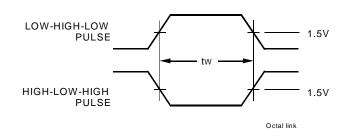
SWITCH POSITION

Test

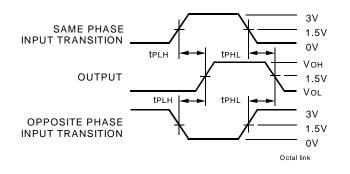
Open Drain

Disable Low

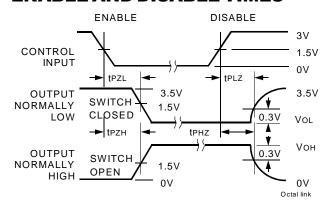
All Other Tests



PROPAGATION DELAY



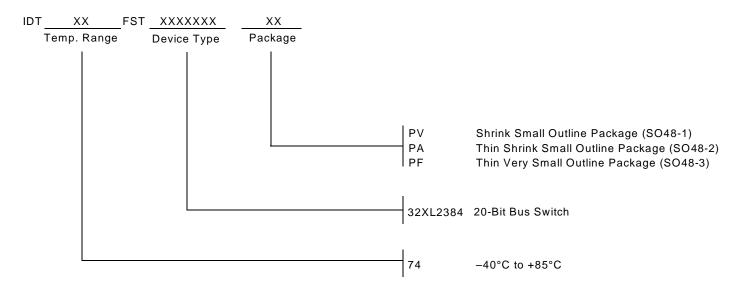
ENABLE AND DISABLE TIMES



NOTES:

- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH
- 2. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; tF ≤ 2.5ns; tR ≤ 2.5ns

ORDERING INFORMATION





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